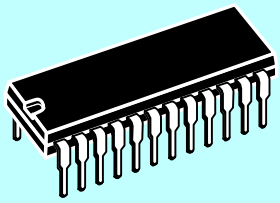
查询PDIP24供应商

Thermal Data

POWER DIP 24
20+2+2 leads



24 leads

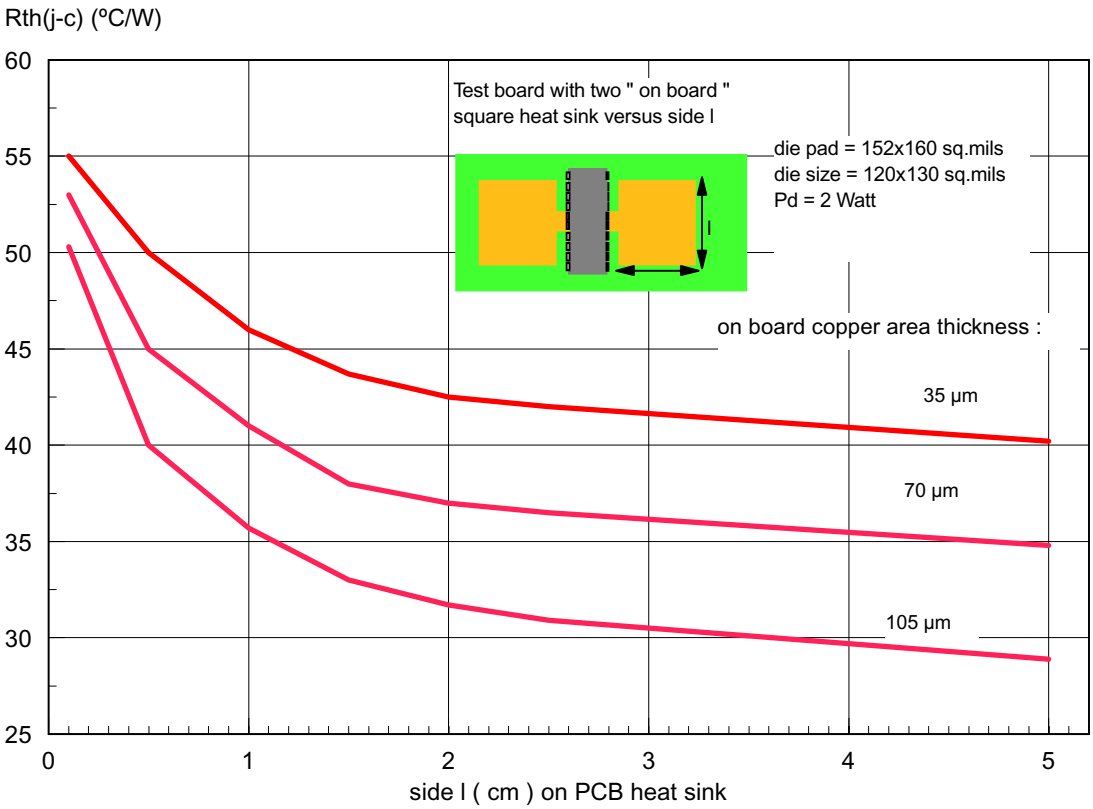
PACKAGE MATERIAL LIST

item #	material	thickness	thermal conductivity
leadframe	copper	0.25 mm	2.6 W/cm°C
die attach	epoxy glue (silver filled)	15-50 µm	0.01 W/cm°C
molding compound	epoxy resin	3 mm	0.0063W/cm°C

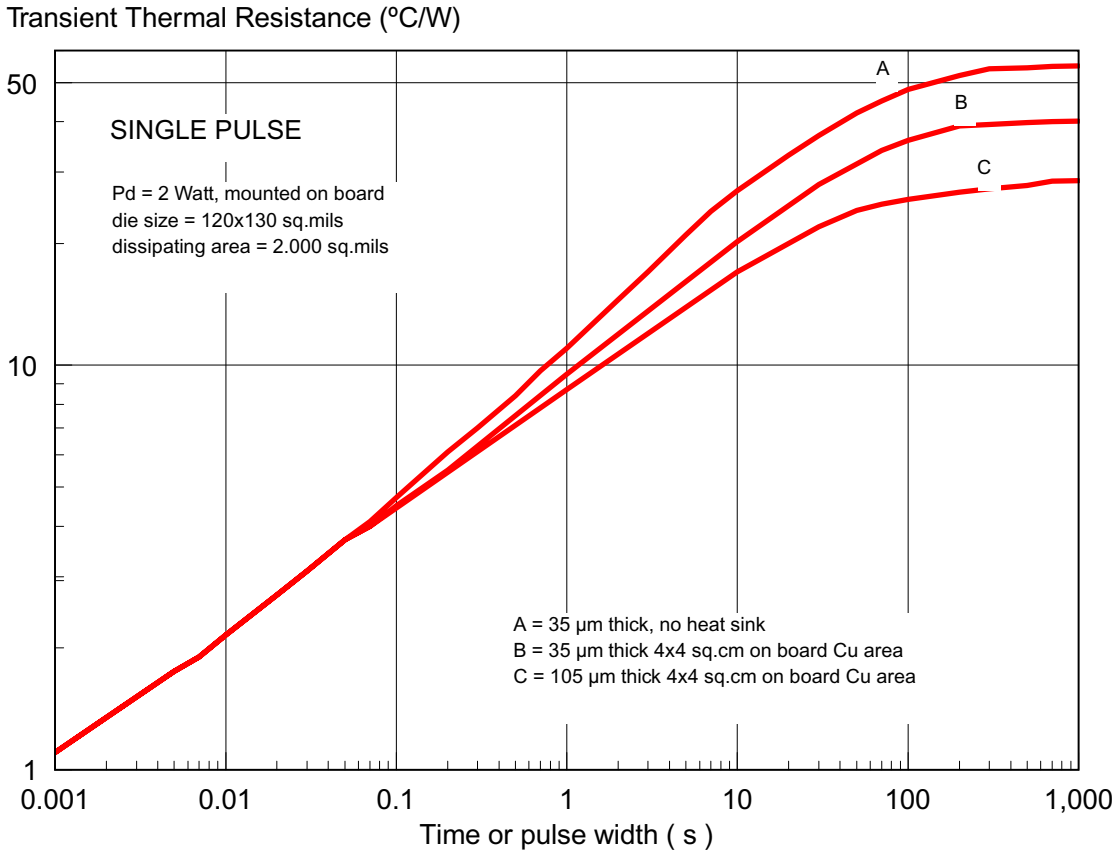
Charts enclosed :

1) Rth(j-a) vs on board heat sink
2) Zth(j-a) vs time width

1)


Rth(j-c) (°C/W)
60
55
50
45
40
35
30
25
0
1
2
3
4
5
side l (cm) on PCB heat sink
Test board with two " on board "
square heat sink versus side l
l
die pad = 152x160 sq.mils
die size = 120x130 sq.mils
Pd = 2 Watt
on board copper area thickness :
35 µm
70 µm
105 µm

2)


Transient Thermal Resistance (°C/W)
50
10
1
0.001
0.01
0.1
1
10
100
1,000
Time or pulse width (s)
SINGLE PULSE
Pd = 2 Watt, mounted on board
die size = 120x130 sq.mils
dissipating area = 2.000 sq.mils
A
B
C
A = 35 µm thick, no heat sink
B = 35 µm thick 4x4 sq.cm on board Cu area
C = 105 µm thick 4x4 sq.cm on board Cu area